

# LOCTITE ECCOBOND UF 8828

September 2012

### PRODUCT DESCRIPTION

LOCTITE ECCOBOND UF 8828 provides the following product characteristics:

Technology	Cyanate Ester	
Appearance	Off-white	
Cure	Heat cure	
Product Benefits	High fracture toughness	
	High flow speed	
	Self-filleting	
	Optimized modulus	
	Low chip warpage	
	<ul> <li>Eliminates the need for secondary fillet dispense process</li> </ul>	
	<ul> <li>260°C reflow capability for Pb-free applications</li> </ul>	
Application	Underfill	
Filler Type	Silica	
pН	6.8	

LOCTITE ECCOBOND UF 8828 moisture resistant underfill encapsulant is formulated to flow consistently without voids on die sizes over 20 x 20mm, while maintaining a fast flow rate.

#### TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	0.9
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	15,000
Work Life @ 25°C, hours	>12
Shelf Life @ -40°C, days	365
Flash Point - See SDS	

#### TYPICAL CURING PERFORMANCE

#### **Cure Schedule**

15 minute ramp to 165°C + 60 minutes @ 165°C

#### Alternative Cure Schedule

Prebake 3 hours @ 165°C; 30 minute ramp to 100°C; hold at 100°C for 60 minutes; 30 minute ramp to 165°C; hold at 165°C for 90 minutes

#### Substrate Temperature

100°C (80°C - 110°C)

#### Weight Loss on Cure

10 x 10 mm Si die on glass slide, %	0.38

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

# TYPICAL PROPERTIES OF CURED MATERIAL

#### **Physical Properties**

Glass Transition Temperature (Tg) by TMA, °C 128
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30 102
N/mm <sup>2</sup> 8,232 (psi) (1,193,660)
N/mm <sup>2</sup> 6,492 (psi) (941,290)
N/mm <sup>2</sup> 410 (psi) (59,460)
N/mm² 117 (psi) (16,970)
<10
<10
<10
42

#### **TYPICAL PERFORMANCE OF CURED MATERIAL**

## Miscellaneous

Die Shear Strength	
2 x 2 mm Ceramic die on BT, kg-f	28
@ 25°C	

Die Shear Strength vs Temperature, kg-f

x 3 mm Ceramic die on BT, kg-f		
@25°C	@250°C	
918	77	

#### GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

#### THAWING:

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- 1. Allow container to reach room temperature before use.
- 2. After removing from the freezer, set the syringes to stand vertically while thawing.
- DO NOT open the container before contents reach 22°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- DO NOT re-freeze. Once thawed to 22°C, the adhesive should not be re-frozen.

#### DIRECTIONS FOR USE

- 1. Thawed adhesive should immediately be placed on dispense equipment for use.
- If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
- 3. Adhesive must be completely used within the products recommended work life.
- 4. The substrates should be preheated prior to dispensing in order to ensure even underfill flow under the die. The preheating time depends on the thermal mass and the heating method. Using a thermocouple to measure the actual temperature on top of the substrate near the dispense area is recommended. The



recommended substrate temperature is typically 100°C (80 to 110°C).

- 5. The underfill volume depends on several factors, including die size, gap height, bump density and fillet height. Dispense pattern will primarily depend on bump layout and die size. Dispensing optimization may be necessary in order to produce void-free parts. A 60 to 80% line (1 to 3 passes) centered along the die size is generally recommended.
- 6. Minimal delay time between passes is recommended to avoid underfill overflow on top of the die (0 to 20 seconds). The recommended needle size is typically 22 to 25 gage.

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

# Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

 $(^{\circ}C x 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm<sup>2</sup> MPa = N/mm<sup>2</sup> N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

### Disclaimer

#### Note:

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